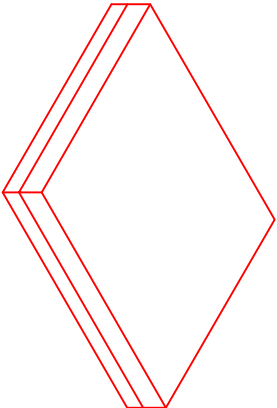


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REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06115	06/06/99	E.B.	MCN



7. REFERENCE SPECIFICATIONS:
A. AIAW SPEC #001-0631-2234: PACKING OPERATION PROCEDURE.
B. AIAW SPEC #001-0619-2068: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMP IS 60.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 8 X 8.
2. THE BASIC SOLDER BUMP GRID PITCH IS 0.50.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

TOLERANCES			APPROVALS			DATE			TITLE		
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS			IS			DATE			DATE		
DECIMAL			N/A			04/19/99			PACKAGE OUTLINE - CTGA 60,		
XX ±0.10			N/A			04/29/99			5.00mm X 5.00mm, 2 LAYER,		
XX ±0.06			N/A			04/29/99			0.50mm PITCH, LAMINATE SUBSTRATE. AAP		
XXX ±0.03			N/A			04/29/99			N/A		
ANGULAR			N/A			04/29/99			N/A		
TYPICAL			N/A			04/29/99			N/A		
DO NOT SCALE DRAWING			N/A			06/06/99			N/A		



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